



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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2SJ0674

Silicon P-channel MOS FET

For switching circuits

■ Features

- Low ON resistance R_{on}
- High-speed switching
- SSSMini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Package

- Code
SSSMini3-F1
- Pin Name
1: Gate
2: Source
3: Drain

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V_{DSS}	-30	V
Gate-source surrender voltage	V_{GSS}	± 12	V
Drain current	I_D	-100	mA
Peak drain current	I_{DP}	-200	mA
Power dissipation	P_D	100	mW
Channel temperature	T_{ch}	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

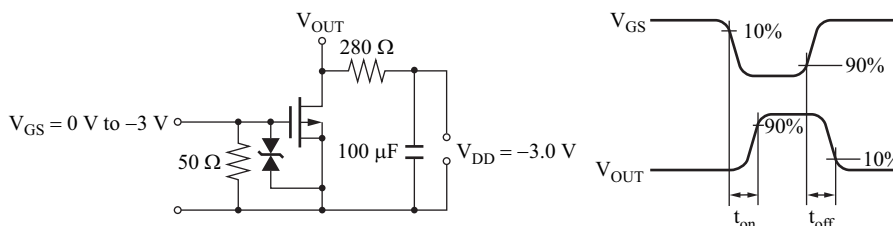
■ Marking Symbol: 5U

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source surrender voltage	V_{DSS}	$I_D = -10 \mu\text{A}, V_{GS} = 0$	-30			V
Drain-source cutoff current	I_{DSS}	$V_{DS} = -20 \text{V}, V_{GS} = 0$			-1.0	μA
Gate-source cutoff current	I_{GSS}	$V_{GS} = \pm 10 \text{V}, V_{DS} = 0$			± 10	μA
Gate threshold voltage	V_{TH}	$I_D = -1.0 \text{mA}, V_{DS} = -3.0 \text{V}$	-0.5	-1.0	-1.5	V
Drain-source ON resistance	$R_{DS(on)}$	$I_D = -10 \text{mA}, V_{GS} = -2.5 \text{V}$		13	30	Ω
		$I_D = -10 \text{mA}, V_{GS} = -4.0 \text{V}$		9	18	
Forward transfer admittance	$ Y_{fs} $	$I_D = -10 \text{mA}, V_{DS} = -3 \text{V}, f = 1 \text{kHz}$	20	40		mS
Short-circuit input capacitance (Common source)	C_{iss}	$V_{DS} = -3 \text{V}, V_{GS} = 0, f = 1 \text{MHz}$		12		pF
Short-circuit output capacitance (Common source)	C_{oss}				13	pF
Reverse transfer capacitance (Common source)	C_{rss}			7		pF
Turn-on time *	t_{on}	$V_{DD} = -3 \text{V}, V_{GS} = 0 \text{V to } -3 \text{V}, I_D = -10 \text{mA}$		300		ns
Turn-off time *	t_{off}	$V_{DD} = -3 \text{V}, V_{GS} = -3 \text{V to } 0 \text{V}, I_D = -10 \text{mA}$		400		ns

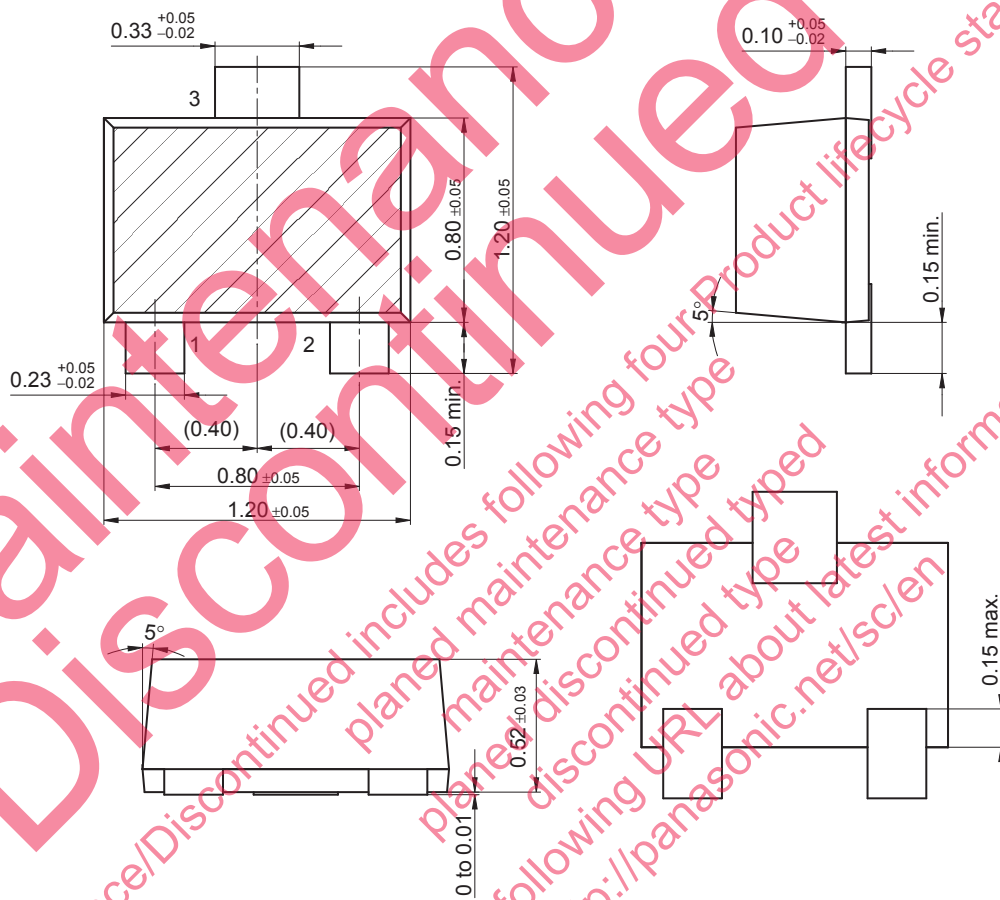
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: t_{on}, t_{off} measurement circuit



SSSMini3-F1

Unit: mm



Maintenance/Discontinued includes following four Product lifecycle stage.
planned maintenance type
planned maintenance type
discontinued type
discontinued type
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maintenance type
planned discontinued type
discontinued type
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